INTERNATIONAL CONFERENCE ON MICROWAVES, COMMUNICATIONS, ANTENNAS & ELECTRONIC SYSTEMS









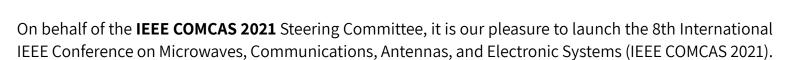












In 2021 the International IEEE COMCAS will continue to evolve and provide an advanced multidisciplinary forum for the exchange of ideas, research results, and industry experience in a range of key areas i.e., communications and sensors, antennas, biomedical engineering, RF and Microwave devices and circuits, thermal management and electronic packaging, signal processing and imaging, as well as radar, acoustics and Microwave system engineering. In its entirety the event includes a technical program, industry exhibits, and guest presentations from global experts on recent academic and industry advancements.

Held from 1-3 November 2021 in Tel Aviv Israel, at the David Intercontinental Hotel by the Mediterranean Sea; IEEE COMCAS is a biennial series tailored to maximize networking, support the candid exchange of ideas, and develop a range of enduring opportunities.

Our Technical Program is paired with a Technical Exhibition that offers companies and agencies a unique opportunity to visit Israel, present relevant products and quality services, and pursue key networking opportunities. Attendees can take part and engage with new contacts, create business opportunities and solidify contracts for the future.

IEEE COMCAS 2019 was our greatest success to date with near 1900 attendees, over 240 lectures in 88 sessions, alongside participants from 39 countries, and exhibitors from more than 100 industry vendors. Following a year of great transformation, we are confident that IEEE COMCAS 2021 will transcend our expectations on both a professional and personal level.

We invite you to join us in Tel Aviv on 1-3 November to take an active part in IEEE COMCAS 2021 and be a part of its success.

IMPORTANT DATES

May 3, 2021 Abstract/Paper Submission for initial reviews

June 1, 2021 Submission of proposals for workshops, short courses and tutorials

July 22, 2021 Accept/revise/reject notifications sent to authors

September 1, 2021 Final revised manuscripts submission deadline

WORKSHOPS, SHORT COURSES, AND TUTORIALS

IEEE COMCAS 2021 will feature invited talks, technical lectures and short courses given by distinguished international experts.

Additional suggestions for workshops and short courses will be considered. For suggestions, please provide a short description of your proposal, including a list of potential talks and speakers, indicating which have already confirmed. Proposals should be submitted to Vadim.Issakov@ovgu.de

GRANTS & AWARDS

The Mini-Circuits Harvey Kaylie Best Paper & Best Student Paper Awards

Awards (1,800 USD each) will be granted on the third conference day.

The European Microwave Association (EuMA) Student Paper Awards

Two awards (1,000 EUR each) will be granted on the third conference day.

Student/Young Scientist Travel Grants

IEEE COMCAS 2021 encourages participation of young scientists to present papers at the conference. Several travel grants will be provided on a competitive basis. Each grant is up to 500 USD.

SPECIAL EVENTS

Young Professionals: Entrepreneurship in Semiconductors

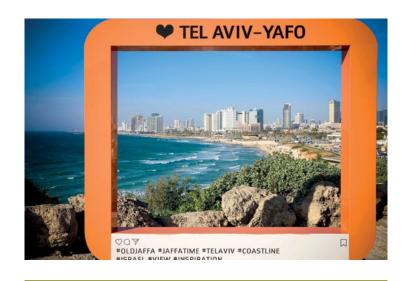
IEEE COMCAS 2021 will again host the popular innovation session by IEEE YP and the ACRC - Advanced Circuits Research Center of the Technion. The special session will feature successful technology and innovation leaders of the Israeli high-tech industry. A perfect place to broaden your professional network while enjoying Tel Aviv.

Women in Engineering (WIE)

Historically, women represent only 10–20% of the overall engineering work force. So how can one make engineering more attractive to young women? How can one increase the number of women in engineering? To seek for the answers, join us for the WIE event! Our speakers are prominent women in electronics and electro-optics engineering who will share and discuss their career challenges and triumphs.

Your Career in Microwaves

Executive workshops on how to start-up your career in the microwave industry held by leading career consultants and industry executives.



SIGHTSEEING OPPORTUNITIES

In launching the 2021 event we would also like to welcome you to the sunshine of the eastern Mediterranean, in Tel Aviv. As a cosmopolitan city of stunning views and endless innovation, Tel Aviv is a center that resonates with an energized atmosphere, streets of storied history, and an internationally recognized nightlife.

Depart from Tel Aviv to discover the whole of Israel... sea and coral reefs, desert and mountains, holy and historic sites of three religions, Israel offers you endless experiences in just a short drive away. Your unique experiences may include floating in the Dead Sea, sleeping under a Bedouin tent, visiting the Holy Sepulcher, walking in the ancient Western Wall tunnels – name your dream.



TECHNICAL PAPERS AND ABSTRACTS

IEEE COMCAS offers seven technical tracks welcoming high quality research, tutorial, and application papers or abstracts. All submitted papers and abstracts will be peer reviewed. Accepted ones will be published in the IEEE COMCAS 2021 Proceedings. Presented full papers will be submitted for inclusion in IEEE Xplore®.

LIST OF TOPICS

Communications and Sensors

Beyond 5G – Systems & Technologies
Al in Communication Networks
Big Data in Communication Networks
MIMO & Space-Time Coding Technologies
5G systems & Millimeter Wave Propagation
Cognitive Radio & Spectral Sharing
Communications Security
First Responder/Military Communications
Green Communication
Internet of Things

Long Range Low Power Networks
Micro/Pico/Femtocell Devices and Systems
Modulation & Signal Processing Technologies
On-Body and Short Range Communications
Radio over Fiber & Optical/Wireless Convergence
Sensor Networks and Technologies
Software-Defined Radio & Multiple Access

Antennas, Propagation, and Scattering

Smart Antennas, Beamforming and MIMO
Wave Propagation and Channel Modeling
Wave Scattering and RCS
NanoEM, Plasmonics, and Applications
Metamaterials, FSS and EBG
EM Field Theory and Numerical Techniques
EM Interference & Compatibility, SI
Spectrum Management and Monitoring
ELF, RF, µWave, mmW and THz Measurements

Electronic Packaging & Thermal Management (P&TM)

P&TM of Electronics on Device and PCB Level
Microelectronics P&TM on Chip Level
P&TM of RF Devices
P&TM of Photonics and Optics
P&TM of Medical Devices
Structural, Joining, and Coating Materials
Destructive and Non-Destructive Testing
Advanced Methods for Thermal Management
Numerical Modeling of Thermal Management
Reliability of Electronic Devices

Biomedical Engineering

Advances in MRI: Technology, Systems and Applications Medical RF, MW & MMW Applications and Devices Medical Imaging and Image Processing

RF/MW Devices and Circuits, RFICs

Solid-State Devices, RFICs

µWave, mmW and Sub-mmW Circuits/Technologies

Nano and THz Devices/Technologies

Microwave Photonics

Passive Components and Circuits

Filters and Multiplexers

Ferroelectrics, RF MEMS, MOEMS, and NEMS

Active Devices and Circuits

RF Power Amplifiers and Devices

Tunable and Reconfigurable Circuits/Systems

Analog/Digital/Mixed RF Circuits

Circuit Theory, Modeling and Applications

Interconnects, Packaging and MCM

CAD Techniques for Devices and Circuits

Emerging Technologies

Microwave Systems, Radar, Acoustics

Aeronautical and Space Applications
RFID Devices/Systems/Applications
Automotive/Transportation Radar & Communications
Environmentally Sensitive ("Green") Design
UWB and Multispectral Technologies & Systems
Emerging System Architectures
Modelling Techniques for RF Systems
Radar Techniques, Systems and Applications
Sonar Systems and Applications
Wireless Power Transfer & Energy Harvesting
Terahertz Systems

Signal Processing (SP) and ImagingMicrowave Imaging and Tomography

Acoustic/Sonar Imaging and Techniques
Radar SP and Imaging, SAR, ATR
MIMO SP for Radar
Ground and Foliage Penetration Systems
Signal Acquisition and Sensor Management
DF, Emitter Location, Elint, Array Processing
Target Detection, Identification and Tracking
Data Fusion
Time Domain and UWB SP

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COMCAS.ORG

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